

Electronic Patent Application Fee Transmittal

Application Number:	10552370			
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Title of Invention:	SOAP-MOLDING DIE			
First Named Inventor/Applicant Name:	Takashi Nakano			
Filer:	Marvin Jay Spivak/Mimi Chanthaphone			
Attorney Docket Number:	279330US3PCT			
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Patent-Appeals-and-Interference:				
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Printed copy of patent - no color	8001	3	3	9
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